

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

Assignment ID: PATI627601

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST
SEQUENCE:	1
CONVEYING PARTY DATA	
Name	Execution Date
TruTag Technologies, Inc.	09/27/2024
RECEIVING PARTY DATA	
Company Name:	Kumukahi Holdings, Inc.
Street Address:	616 Moaniala Street
City:	Honolulu
State/Country:	HAWAII
Postal Code:	96821
PROPERTY NUMBERS Total: 13	
Property Type	Number
Patent Number:	9677935
Patent Number:	10012542
Patent Number:	9799541
Patent Number:	11125753
Patent Number:	8926803
Patent Number:	8999058
Patent Number:	9869031
Patent Number:	9076642
Patent Number:	9771662
Patent Number:	10138565
Patent Number:	8906218
Patent Number:	9890465
Patent Number:	10829864
CORRESPONDENCE DATA	
Fax Number:	5107359389
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(415)613-4296
Email:	pwong@trutags.com

Correspondent Name:	Mr. Peter Wong
Address Line 1:	TruTag Technologies, Inc.
Address Line 2:	2200 Powell Street, Suite 1035
Address Line 4:	Emeryville, CALIFORNIA 94608
NAME OF SUBMITTER:	Peter Wong
SIGNATURE:	Peter Wong
DATE SIGNED:	11/12/2024
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 4 source=KHI-TruTag Notice of Grant of Security Interests in Patents (September 27, 2024) FSIGNED#page1.tiff source=KHI-TruTag Notice of Grant of Security Interests in Patents (September 27, 2024) FSIGNED#page2.tiff source=KHI-TruTag Notice of Grant of Security Interests in Patents (September 27, 2024) FSIGNED#page3.tiff source=KHI-TruTag Notice of Grant of Security Interests in Patents (September 27, 2024) FSIGNED#page4.tiff	

NOTICE OF GRANT OF SECURITY INTERESTS IN PATENTS

THIS NOTICE OF GRANT OF SECURITY INTERESTS IN PATENTS (this "Agreement") dated as of September 27, 2024, is made by and between TruTag Technologies, Inc., a Delaware corporation ("Debtor"), and Kumukahi Holdings, Inc., a Hawaii corporation ("Secured Party").

RECITALS:

A. Pursuant to that certain Security Agreement dated as of February 22, 2024 (the "Security Agreement"), Debtor granted to Secured Party a security interest in certain property and assets of Debtor to secure a loan made by Secured Party to Debtor, including all patents, patent applications and like protections owned by Debtor ("Patents").

B. Secured Party has agreed to release certain Patents in connection with the sale of certain assets of Debtor (the "Sale").

C. The parties now wish to confirm that the Patents that will continue to be subject to the security interest of Secured Party after the closing of the Sale and partial release.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, Debtor and Secured Party agree as follows:

1. Definitions. Unless otherwise defined herein, initially capitalized terms used herein shall have the meaning ascribed to them in the Security Agreement.

2. Confirmation of Security Interest. Debtor hereby confirms that pursuant to the Security Agreement, Debtor granted a security interest in all of the Patents owned by Debtor that are listed in Exhibit A attached hereto (the "Collateral"), and all proceeds and products of such Patents, as collateral for repayment of the amounts owed by Debtor to Secured Party, and such security interest in the Collateral continues in effect and shall not be released in connection with the Sale.

3. Notice. This Agreement has been executed by the parties for the purpose of providing notice of the security interest by recordation of this Agreement in the United States Patent and Trademark Office.

4. Affirmation. Debtor does acknowledge and affirm the rights and remedies of Secured Party with respect to the security interest in the Collateral as set forth in the Security Agreement, the terms of which are incorporated hereby by reference.

5. Counterparts; Electronic Signatures. This Agreement may be executed in counterparts, each of which will be deemed an original, but all of which together constitute one and the same original. This Agreement may be executed and delivered by electronic means.

[Signatures on the following page.]

The undersigned have executed this Agreement as of the date set forth above.

TRUTAG TECHNOLOGIES, INC.,
a Delaware corporation

By: DocuSigned by:

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Name: Barry McDonogh
Title: Chief Executive Officer

“Debtor”

KUMUKAHI HOLDINGS, INC.,
a Hawaii corporation

By: _____
Name: James Pappas
Title: President

"Secured Party"


The undersigned have executed this Agreement as of the date set forth above.

TRUTAG TECHNOLOGIES, INC.,
a Delaware corporation

By _____
Name: Barry McDonogh
Title: Chief Executive Officer

"Debtor"

KUMUKAHI HOLDINGS, INC.,
a Hawaii corporation

By: 
Name: James Pappas
Title: President

"Secured Party"

EXHIBIT A

Debtor Patents

Country	Status	Application No.	Filed Date	Patent No.	Granted Date	Title
United States of America	Granted	14/581,935	12/23/2014	9,677,935	06/13/2017	FABRY-PEROT SPECTRAL IMAGE MEASUREMENT
United States of America	Granted	15/594,345	05/12/2017	10,012,542	07/03/2018	FABRY-PEROT SPECTRAL IMAGE MEASUREMENT
United States of America	Granted	14/576,054	12/18/2014	9,799,541	10/24/2017	MULTIPLE WAFER SINGLE BATH ETCHER
United States of America	Granted	15/934,538	03/23/2018	11,125,753	09/21/2021	LABELING USING AN OPTICAL THICKNESS MEASUREMENT OF A BIOSENSOR
United States of America	Granted	12/688,495	01/15/2010	8,926,803	01/06/2015	POROUS SILICON ELECTRO-ETCHING SYSTEM AND METHOD
United States of America	Granted	12/774,667	05/05/2010	8,999,058	04/07/2015	HIGH-PRODUCTIVITY POROUS SEMICONDUCTOR MANUFACTURING EQUIPMENT
United States of America	Granted	14/679,731	04/06/2015	9,869,031	01/16/2018	HIGH-PRODUCTIVITY POROUS SEMICONDUCTOR MANUFACTURING EQUIPMENT
United States of America	Granted	13/244,466	09/24/2011	9,076,642	07/07/2015	HIGH-THROUGHPUT BATCH POROUS SILICON MANUFACTURING EQUIPMENT DESIGN AND PROCESSING METHODS
United States of America	Granted	14/792,412	07/06/2015	9,771,662	09/26/2017	HIGH-THROUGHPUT BATCH POROUS SILICON MANUFACTURING EQUIPMENT DESIGN AND PROCESSING METHODS
United States of America	Granted	15/398,681	01/04/2017	10,138,565	11/27/2018	HIGH-THROUGHPUT BATCH POROUS SILICON MANUFACTURING EQUIPMENT DESIGN AND PROCESSING METHODS
United States of America	Granted	13/288,721	11/03/2011	8,906,218	12/09/2014	APPARATUS AND METHODS FOR UNIFORMLY FORMING POROUS SEMICONDUCTOR ON A SUBSTRATE
United States of America	Granted	14/563,888	12/08/2014	9,890,465	02/13/2018	APPARATUS AND METHODS FOR UNIFORMLY FORMING POROUS SEMICONDUCTOR ON A SUBSTRATE
United States of America	Granted	15/851,023	12/21/2017	10,829,864	11/10/2020	APPARATUS AND METHODS FOR UNIFORMLY FORMING POROUS SEMICONDUCTOR ON A SUBSTRATE

PATENT

RECORDED: 11/12/2024

REEL: 069240 FRAME: 0898